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(12) **United States Design Patent** (10) **Patent No.:** **US D916,039 S**  
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(54) **SEMICONDUCTOR DEVICE**

(56) **References Cited**

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(72) Inventors: **Tomohiro Yamanaka, Osaka (JP); Yoichi Makimoto, Osaka (JP)**

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(\*\*) Term: **15 Years**

(21) Appl. No.: **29/728,654**

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(51) **LOC (13) Cl.** ..... **13-03**

*Primary Examiner* — Elizabeth J Oswecki

(52) **U.S. Cl.**  
USPC ..... **D13/182**

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(58) **Field of Classification Search**  
USPC ..... D13/182  
CPC ..... H01L 21/00; H01L 21/02; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 2224/42; H01L 2224/43; H01L 2224/01; H01L 2224/08055; H01L 2224/08054; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 23/00; H01L 23/48; H01L 23/4926; H01L 23/495; H01L 23/49517; H01L 23/498; H01L 23/49805; H01L 23/49811; H01L 23/49861; H01L 23/49866; H01L 23/49872; H01L 23/49575; H01L 23/49579; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905

(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a semiconductor device, showing our new design;  
FIG. 2 is a rear view thereof;  
FIG. 3 is a top view thereof;  
FIG. 4 is a bottom view thereof;  
FIG. 5 is a left-side view thereof;  
FIG. 6 is a right-side view thereof;

See application file for complete search history.

(Continued)

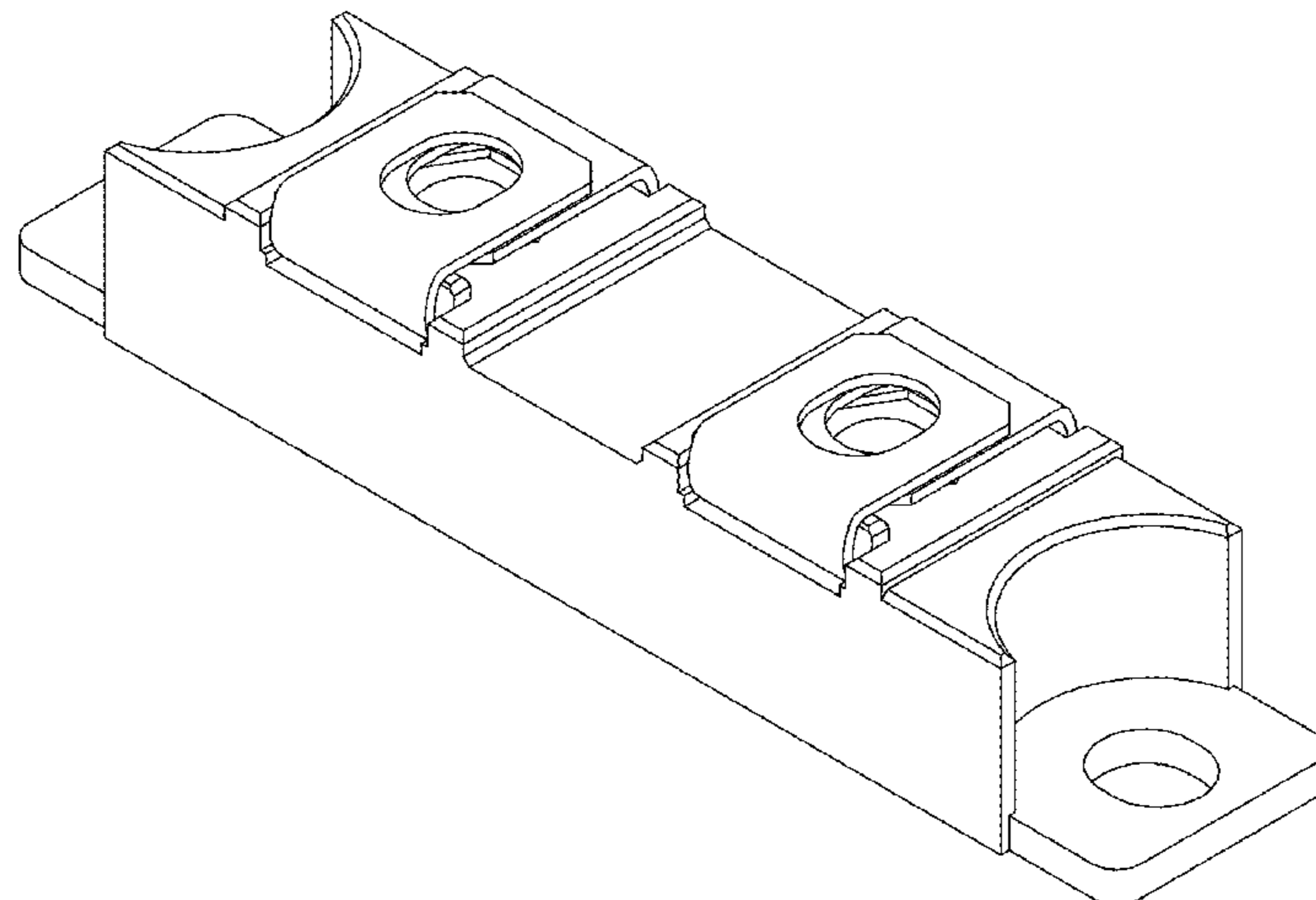


FIG. 7 is a front top perspective view thereof;  
FIG. 8 is a rear top perspective view thereof; and,  
FIG. 9 is a rear side perspective view thereof.

**1 Claim, 9 Drawing Sheets**

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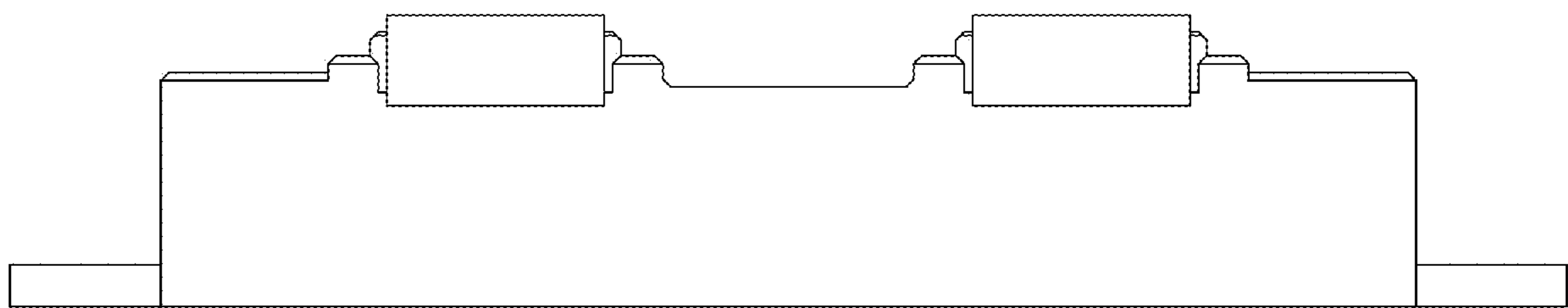


FIG. 1

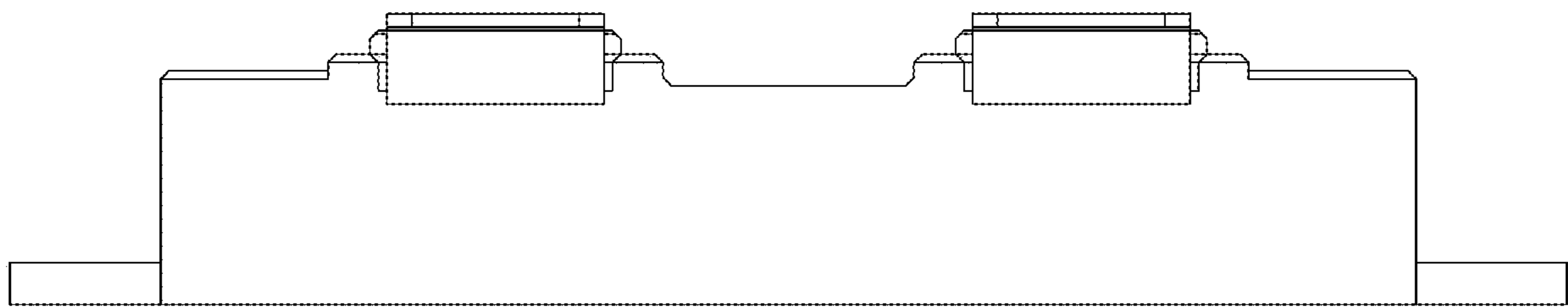


FIG. 2

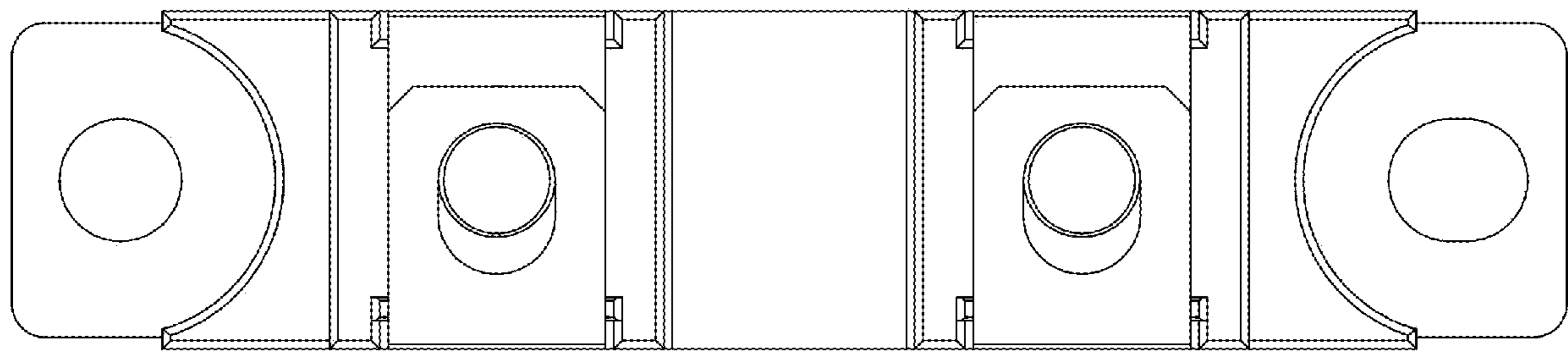


FIG. 3

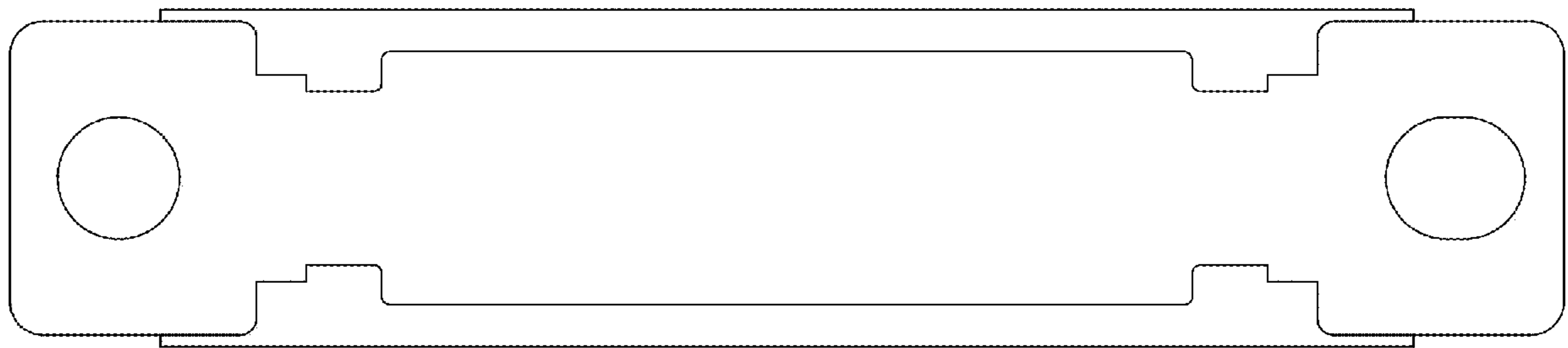


FIG. 4

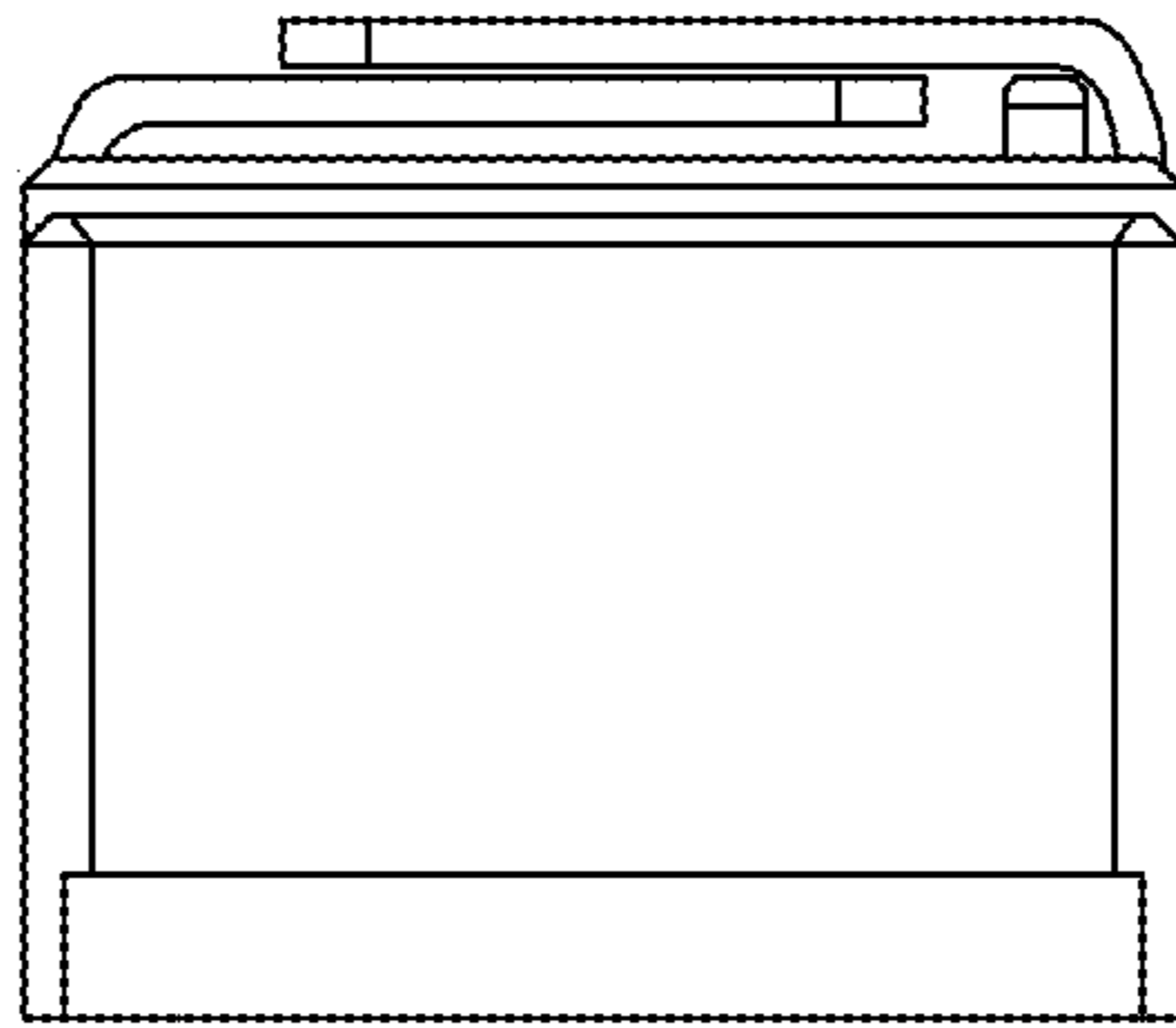


FIG. 5

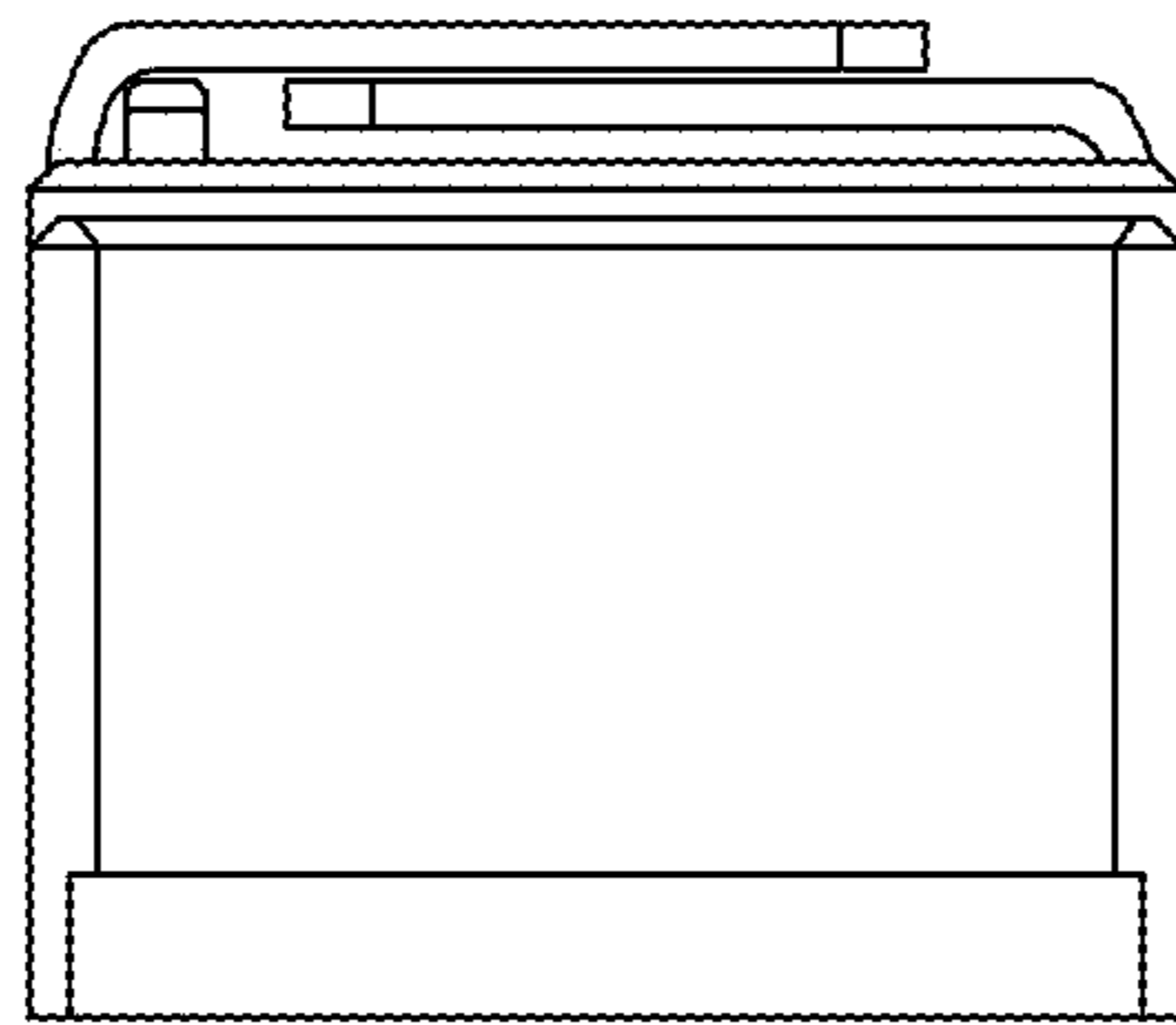


FIG. 6



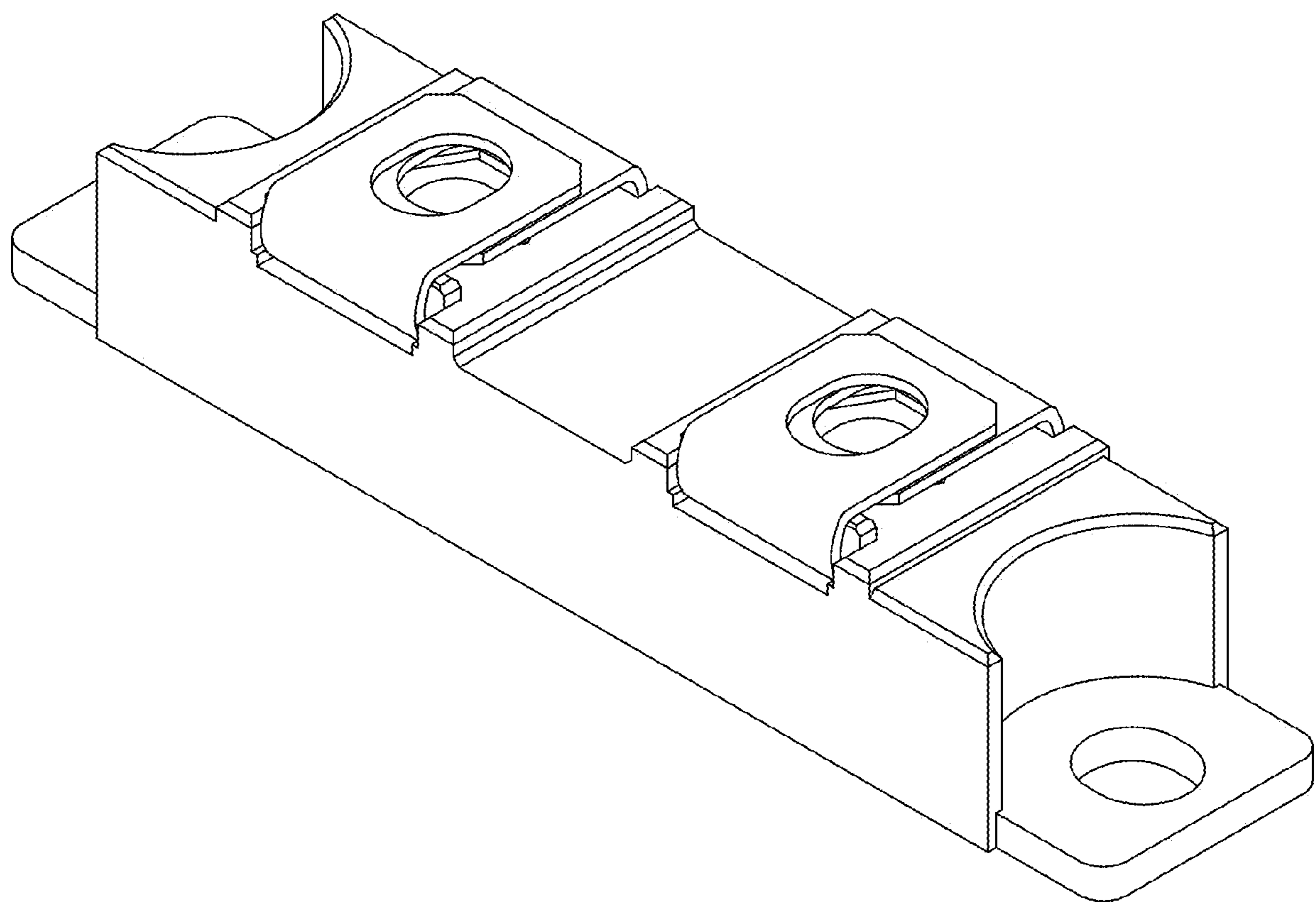


FIG. 7

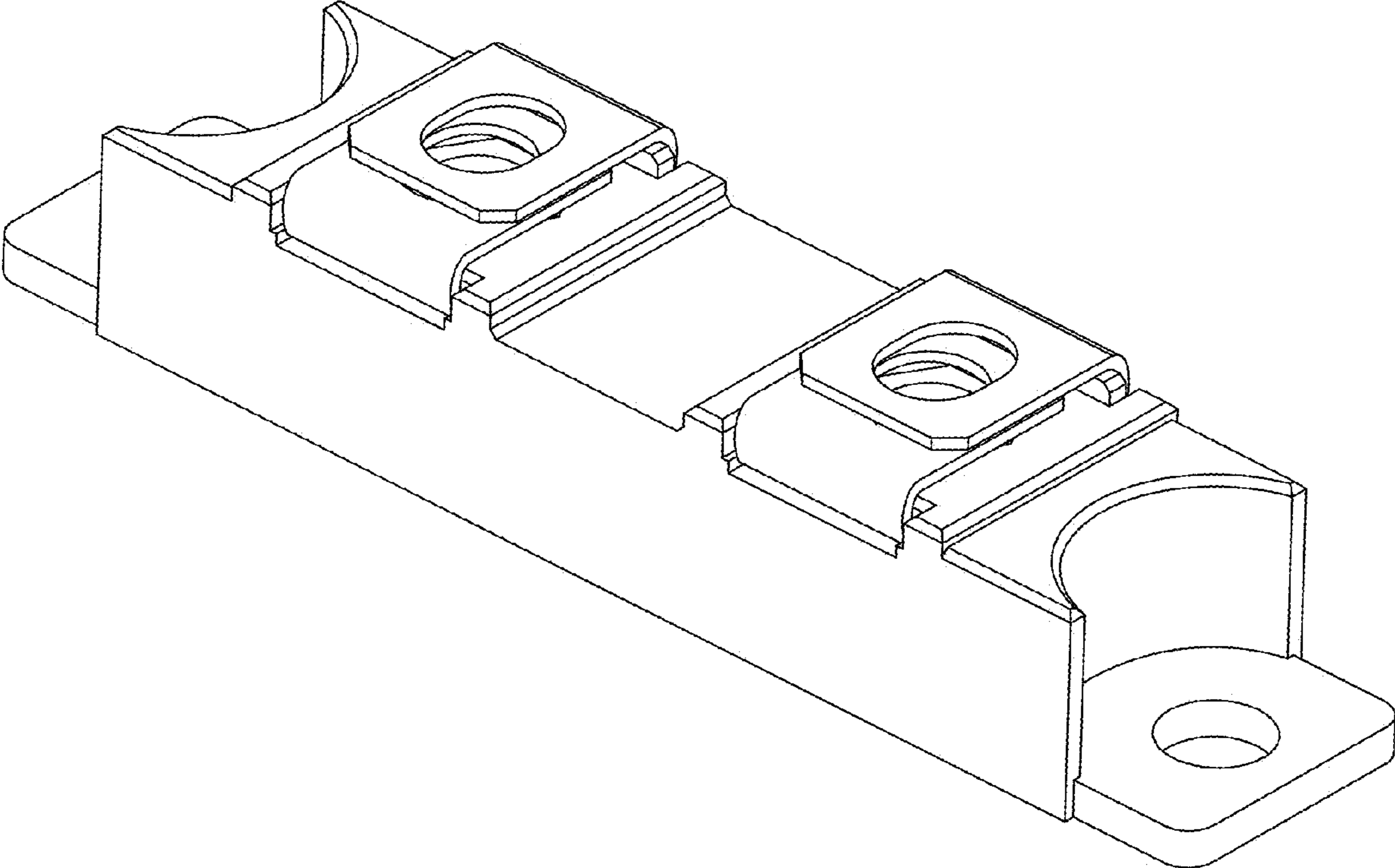


FIG. 8

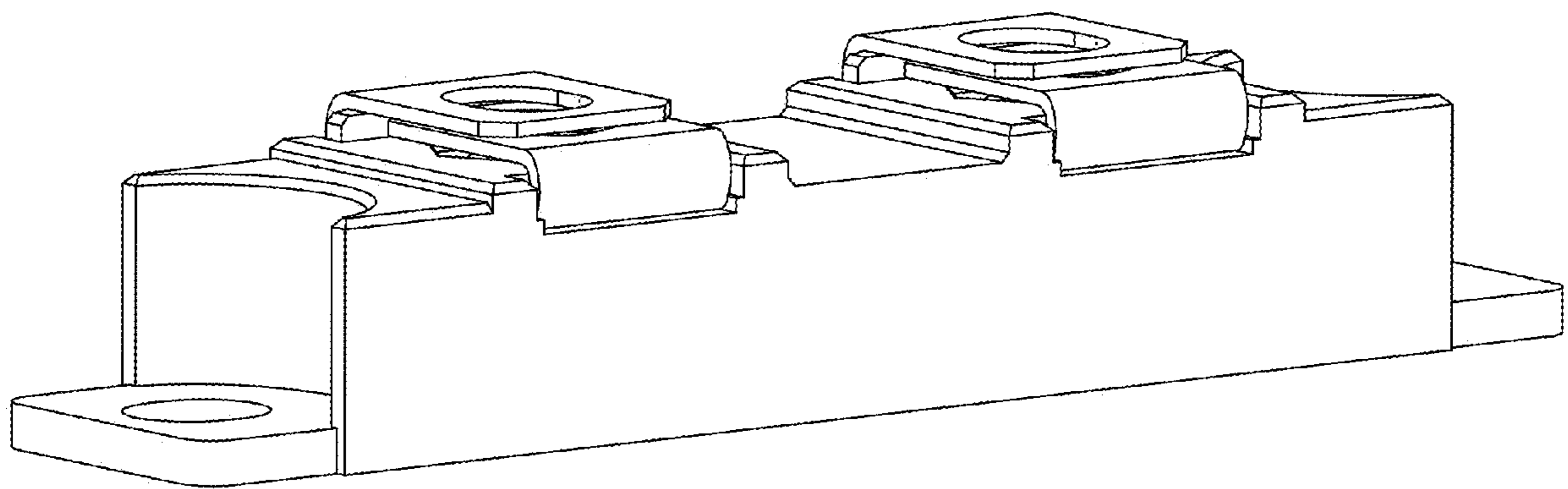


FIG. 9